



# Intel Announces First Commercial Availability of 4G LTE Modem; Introduces Module for 4G Connected Tablets and Ultrabooks™

## NEWS HIGHLIGHTS

- Intel® XMM™ 7160 LTE modem is now shipping in the 4G version of the Samsung GALAXY Tab 3 (10.1) – available in Asia and Europe.
- Intel® XMM™ 7160 provides multimode (2G/3G/4G LTE) voice and data with simultaneous support for 15 LTE bands for global LTE roaming.
- Intel announces PCIe M.2 LTE wireless data modules expected to ship in 2014 tablet and Ultrabook™ designs from leading manufacturers.

SANTA CLARA, Calif.--(BUSINESS WIRE)-- Intel Corporation today announced the commercial availability of its multimode, multiband 4G LTE solution. The Intel® XMM™ 7160 platform is featured in the LTE version of the [Samsung GALAXY Tab 3 \(10.1\)\\*](#), now available in Asia and Europe.

Intel has also expanded its portfolio of 4G LTE connectivity solutions, introducing PCIe (PCI Express) M.2 modules for 4G connected tablets, Ultrabooks™ and 2 in 1 devices as well as an integrated radio frequency (RF) transceiver module, the Intel® SMARTi™ m4G. These new products make it simple, efficient and cost effective for device manufacturers to add high performance wireless connectivity to their product designs.

“As LTE networks expand at a rapid pace, 4G connectivity will be an expected ingredient in devices from phones to tablets as well as laptops,” said Hermann Eul, vice president and general manager of Intel’s Mobile and Communications Group. “Intel is providing customers an array of options for fast, reliable LTE connectivity while delivering a competitive choice and design flexibility for the mobile ecosystem.”

The commercial availability of the Intel XMM 7160 solution follows successful interoperability testing with major infrastructure vendors and tier-one operators across Asia, Europe and North America. The Intel XMM 7160 is one of the world’s smallest and lowest-power multimode, multiband LTE solutions for phones and tablets. The solution provides seamless connectivity across 2G, 3G and 4G LTE networks, supports 15 LTE bands simultaneously and is voice-over LTE (VoLTE) capable. It features a highly configurable RF architecture, running real-time algorithms for envelope tracking and antenna tuning that enables cost-efficient multiband configurations, extended battery life and global LTE roaming in a single SKU.

Intel offers a broad portfolio of mobile platform solutions including SoCs, cost-optimized integrated circuits, reference designs and feature-rich software stacks supporting 2G, 3G and 4G LTE. Building on the Intel XMM 7160 platform, Intel today announced two multimode LTE solutions that pave the way for 4G connected devices in a variety of form factors.

### **New Intel PCIe M.2 LTE Modules and Intel SMARTi m4G Solution**

Intel introduced Intel PCIe M.2 LTE modules, which are small, cost-effective, embedded modules in a standardized form factor for adding multimode (2G/3G/4G LTE) data connectivity across a variety of device types. The Intel M.2 module supports peak downlink speeds of 100Mbps over LTE. The modules support up to 15 LTE frequency bands for global roaming. In addition, those modules also feature support for Global Navigation Satellite Systems (GNSS) based on the Intel CG1960 GNSS solution.

For manufacturers, the M.2 module makes it simple to add 4G connectivity to their designs while reducing integration and certification expenses, and improving time-to-market. The M.2 module is currently undergoing interoperability testing with tier-one global service providers. Intel M.2-based modules will soon be available from Huawei\*, Sierra Wireless\* and Telit\*. These modules are expected to ship globally in 2014 tablet and Ultrabook designs from leading manufacturers.

In addition to the new Intel PCIe M.2 LTE module, Intel also offers the new Intel SMARTi m4G - a highly integrated radio transceiver module. The Intel SMARTi m4G was developed in cooperation with [Murata](#)\* and integrates the Intel SMARTi 4G transceiver with most front-end components in one LTCC (low temperature co-fired ceramic) package. When paired with the Intel® X-GOLD™ 716 baseband, manufacturers can meet the certification requirements of service providers with minimal design cycles in an easy-to-place, low-profile solution. With the Intel SMARTi m4G, the overall component count can be reduced by more than 40 components and the required PCB area is reduced up to 20 percent .

Intel plans to deliver next-generation LTE solutions, including the Intel® XMM™ 7260 in 2014. The Intel XMM 7260 adds LTE Advanced features, such as carrier aggregation, faster speeds and support for both TD-LTE and TD-SCDMA. More information about Intel's mobile communications solutions is available [here](#).

### **About Intel**

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